Final Program

2021 22nd International Symposium on

QUALITY ELECTRONIC DESIGN

April 7-9, 2021 Virtual Conference California Pacific Daytime San Jose, CA USA

ELECTRON

SOCIETY

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WELCOME TO ISQED'21

On behalf of the ISQED conference and technical committees, we are pleased to welcome you to the 22nd anniversary of the International Symposium on Quality Electronic Design, ISQED'21.

For the past 22 years, ISQED has been the leading voice and pioneer in Quality Electronic Design (QED). With the drastic increase in complexity of semiconductor technology and design, following QED and its underlying principles are becoming more necessary and essential as never before. ISQED'21 strives to lead the community in that direction with a comprehensive program consisting of keynotes, panel, tutorials, and over 100 peer-reviewed articles.

The conference is held in Virtual format, with the technical sponsorship of the IEEE Electron Devices Society, the IEEE Circuits and Systems Society, IEEE Reliability Society, and In-cooperation with ACM/SigDA. Conference proceedings & Papers will published in IEEE Xplore digital library and indexed by Scopus.

ISQED'21 is organized around the important trends in AI/ML, Autonomous Vehicles, Security, IoT, and Quantum Computing. The conference program consists of two keynote talks, four embedded tutorials and a panel discussion, and many Peer-reviewed technical papers with focus on these timely and hot topics.

We are pleased to see an increase in the number of papers submitted to the conference this year. The two- and half-day technical program with four parallel sessions packs over 100 peer-reviewed papers highlighting the latest trends in electronic circuit and system design & automation, testing, verification, sensors, security, semiconductor technologies, cyber-physical systems, etc.

All technical presentations, plenary sessions, panel discussions, tutorials and related events will take place on April 7-9, conducted virtually, at Pacific Daylight Time (PDT).

We would like to thank the ISQED'21 corporate sponsors: Synopsys, Siemens EDA, and Innovotek for their valuable financial support of this conference. Welcome to another exciting year of ISQED and thanks for your support and participation.

General Chair Swaroop Ghosh Pennsylvania State University

TPC -Co-Chair *Abhilash Goyal,* Velodyne LiDAR

Special Sessions Chair *Pravin Kumar Venkatesan* Velodyne LiDAR

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ISQED'21 Best Papers

<u>3B.3</u>

Six-track Standard Cell Libraries with Fin Depopulation, Contact over Active Gate, and Narrower Diffusion Break in 7nm Technology

Tzu-Hsuan Wang, Chih-Chun Hsu, Li Kao, Bing-Yu Li, Tung-Chun Wu, Tsao-Hsuan Peng, Rung-Bin Lin **Yuan Ze University, Taoyuan City, Taiwan**

<u>1A.2</u>

Design Space Extrapolation for Power Delivery Networks using a Transposed Convolutional Net Osama Waqar Bhatti¹, and Madhavan Swaminathany² ¹School of Electrical and Computer Engineering ²School of Material Science and Engineering 3D Systems Packaging Research Center, Georgia Institute of Technology, Atlanta, USA

BEST WIP PAPER

<u>PW4.4</u> Large-Scale Quantum System Design on Nb-based Superconducting Silicon Interconnect Fabric Yu-Tao Yang, Subramanian S. Iyer Department of Electrical and Computer Engineering University of California, Los Angeles (UCLA)

Authors of best papers are acknowledged on Wednesday April 7.

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Panel Chair Shigeki Tomishima Intel Corporation

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China Chair *Gaofeng Wang* Hangzhou Dianzi University **Brazil & South America Chair** *Fabiano Passuelo Hessel* Pontificia Universidade Catolica do Rio do Sul, Brazil

Japan Chair *Masahiro Fujita* University of Tokyo Taiwan Chair Shih-Hsu Huang Chung Yuan Christian University

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Cognitive Computing Hardware (CCH)

Deliang Fan, Arizona State University (Chair) Zhen Zhou, Intel Corp (Co-Chair)

Committee Members: Hongyu An - Michigan Technological University Abishai Daniel - Intel Caiwen Ding - University of Connecticut Xin Fu - University of Houston Miao Hu - Binghamton University Hyeran Jeon - University of California Merced Doo Seok Jeong - Hanyang University Hao Jiang - San Francisco State University Omid Kavehei - The University of Sydney Amey Kulkarni - NVIDIA Inc Xue Lin - Northeastern University Ishan Thakkar - University of Kentucky Yang (Cindy) Yi - Virginia Tech

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Electronic Design Automation Tools and Methodologies (EDA)

Srini Krishnamoorthy, Intel Corp. (Chair) Srinivas Katkoori, University of South Florida (Co-Chair)

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Design Test and Verification (DTV)

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Emerging Device and Process Technologies and Applications (EDPT)

Rasit Onur Topaloglu, IBM (Chair) Vita Pi-Ho Hu, National Taiwan University (Co-Chair)

Committee Members:

Arijit Banerjee - Advanced Micro Devices Rajan Beera - Pall Corporation Abishai Daniel - Intel Tuhin Guha Neogi - Intel Corporation Sumeet Gupta - Purdue University Nikos Konofaos - Aristotle University of Thessaloniki Chun-Yu Lin - National Taiwan Normal University Mehran Mozaffari Kermani - RIT Mahdi Nikdast - Colorado State University Chenyun Pan - University of Texas at Arlington Kun Qian - GLOBALFOUNDRIES Arman Roohi - University of Nebraska - Lincoln Swatilekha Saha - Cypress Semiconductor Corporation Jinhui Wang - University of South Alabama Lan Wei - University of Waterloo Mustafa Berke Yelten - Istanbul Technical University

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Circuit Design, 3D Integration and Advanced Packaging (ICAP)

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Committee Members: Ali Afzali-Kusha - University of Tehran Pawan Agarwal - Maxlinear Inc Divya Akella Kamakshi - University of Virginia Iraklis Anagnostopoulos - Southern Illinois University Carbondale Karan Bhatia - Texas Instruments, Inc. Paulo Butzen - Universidade Federal do Rio Grande Sul Pradeep Chawda - Apple Inc Yuanqing Cheng - Beihang University Minki Cho - Intel Corp. Abishai Daniel - Intel Shomit Das - AMD Research Marshnil Dave - Lion Semiconductor Mike DiRenzo - Texas Instruments Md Amimul Ehsan - Intel Corporation Vittorio Ferrari - University of Brescia Tobias Gemmeke - RWTH Aachen University Patrick Girard - LIRMM / CNRS Na Gong - University of South Alabama Srinivasan Gopal - Intel Corporation Rekha Govindaraj - Apple Inc. Jie Gu - Northwestern University Zhong Guan - UC Santa Barbara Ankush Gupta - Texas Instruments Jos Huisken - Eindhoven University of Technology Rouwaida Kanj - American University of Beirut Dae Hyun Kim - Washington State University Rakesh Kumar - Ampere Computing Joshua Lee - City University of Hong Kong Jin-Fu Li - National Central University Rakeshkumar Mahto - California State University Maria Malik - Intel **Everton Matos - Technology Innovation Institute** Shreepad Panth - Altera Corporation, An Intel Company Harsh Patel - AMD Jose Pineda de Gyvez - NXP Semiconductors Thilo Sauter - Danube University Krems Abhronil Sengupta - The Pennsylvania State University Ali Shahi - GlobalFoundries Prabha Sundaravadivel - University of Texas at Tyler Vishnoi Upasna - Marvell Semiconductor Inc. Jianyong Xie - Intel Amir Zjajo - Delft University of Technology

System-level Design and Methodologies (SDM)

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Rajeev Murgai - Synopsys India Pvt. Ltd.

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<u>Hardware and System Security (HSS)</u>

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Special Sessions

Pravin Kumar Venkatesan, Velodyne Lidar (Chair) Prabha Sundaravadivel, University of Texas at Tyler (Co-Chair) Rajat Subhra Chakraborty, IIT Kharagpur (Co-Chair) Mimi Xie, The University of Texas at San Antonio (Co-Chair)

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WIP - Work in Progress

Sara Tehranipoor, Santa Clara University (Chair) Kurt Schwartz, Texas Instruments (Co-Chair) Ali Iranmanesh, ISQED (Co-Chair)

GENERAL INFORMATION

GENERAL INFORMATION ISQED'21

April 7-9, 2021 Pacific Daylight Time (PDT) Virtual Event

AWARDS & RECOGNITIONS

Wednesday April 7, 9:00 AM - 9:20 AM Track G

Best Paper Awards

Recipients of the ISQED'21 Best Paper Awards will be recognized in this segment of the program. The best papers are shown in Page 2 of this document.

Keynotes

Wednesday, April 7, 9:20 AM - 9:55 AM

Track G Confluence of AI/ML with EDA and Software Engineering

Arun Venkatachar

Vice President, Artificial Intelligence and Central Engineering

Synopsys

Thursday April 8, 9:00 AM - 9:35 AM

Track G

Cars Driving Chips or Chips Driving Cars?

Ravi Subramanian, Ph.D

Senior Vice President - IC Verification Siemens EDA

Panel Discussion

Wednesday, April 7, 12:55 PM - 2:25 PM Track G

State of Autonomous Vehicle Development: Moving Forward with Safe Cars

The automotive industry is going through a disruptive phase and one of the major factors causing this disruption is autonomous cars. The digitalization of the automotive industry is changing the traditional patterns of transport and mobility, and connected vehicles, self-driving vehicles, and vehicles that are increasingly connected to the internet and equipped with electromechanical controls are defining some of today and most of the future automotive industry. Though there is strong demand from users, how realistic is the future of autonomous vehicles? Is the safety of autonomous cars an issue for drivers and will potential safety issues cause the autonomous vehicle development to crash? Is the mobility trend shifting towards ride sharing? What new challenges and opportunities do driverless cars bring to the microelectronic industry? What are the safety and security constraints? What are the implications of the inclusion of AI hardware and software? Join us to listen to our panelist's thoughts on the subject.

Panelists:

Nirmal R. Saxena - NVIDIA Lee Harrison - Mentor, A Siemens Business James Herman - CMU/Roborace Sweta Mehta - Tata Consultancy Services Srijani Dey - DXC Technology

<u>Moderator:</u> Aditya Sharma - Microsoft (Chair)

<u>Chairs:</u> Shigeki Tomishima - Intel Corporation (Chair) Siddha Ganju - Nvidia (Co-Chair)

GENERAL INFORMATION

Embedded Tutorials

Chair & Moderators:

José Pineda de Gyvez - NXP Semiconductors (Co-Chair) Yu Pu - Alibaba (Co-Chair)

Track G

Tutorial 1

Wednesday, April 7, 11:50 PM - 12:50 PM

Semiconductors for the next wave in Automotive

Clara Otero Perez

NXP Semiconductors

Tutorial 2

Thursday April 8, 12: 35 PM 1:35 PM

Large-Scale Quantum Computers: The need for Cryo-CMOS

Dr. Fabio Sebastiano

Delft University of Technology, Delft, The Netherlands

Tutorial 3

Friday April 9, 9:00 AM - 10:00 AM

Putting Al on Diet: TinyML and Efficient Deep Learning

Prof. Song Han, MIT EECS

•••••

Tutorial 4

Friday April 9, 10:00 AM - 11:00 AM

Security challenges and opportunities at the Intersection of Architecture and ML/AI Nael Abu-Ghazaleh

University of California, Riverside

TECHNICAL SESSIONS

There are a total of 16 paper sessions held on Wednesday to Friday. Technical sessions are held in the format of four parallel virtual tracks **A**, **B**, **C**, **D**.

PROGRAM AT A GLANCE - WEDNESDAY

SQED' DATE	SQED'21 PROGRAN	RAM AT A GLANCE			
WEDNESDAY	9:00 AM - 9:20 AM		WELCOME AND INTRODUCTION	ICTION	
4/7/2021			KEVNOTE SPEECH - PLENARY SESSION P1 TRACK G	SESSION P1	
	9:20 AM - 9:55 AM	ARUN VENKATACH	CONFLUENCE OF AI/ML WITH EDA AND SOFTWARE ENGINEERING ARUN VENKATACHAR - VICE PRESIDENT, ARTIFICIAL INTELLIGENCE AND CENTRAL ENGINEERING , SYNOPSYS TRACK G	SOFTWARE ENGINEERING ENCE AND CENTRAL ENGINEERING	SYROPSYS
	9:55 AM - 10:00 AM		BREAK		
		SESSION 1A	SESSION 1B	SESSION 1C	SESSION 1D
	10: AM - 11:20 AM	ADVANCED ANALOG DESIGN AND CONCEPTS	VERIFICATION AND FAULT ANALYSIS OF CIRCUITS	EMERGING DEVICES AND TECHNOLOGIES	APPLIED MACHINE LEARNING FOR HARDWARE CYBERSECURITY
		TRACK A	TRACK B	TRACK C	TRACK D
	11:20 AM - 11:50 AM		BREAK		
	11:50 AM -12:55 PM		EMBEDDED TUTORIAL1 SEMICONDUCTORS FOR THE NEXT WAVE IN AUTOMOTIVE CLARA OTERO PEREZ - NXP SEMICONDUCTORS	<u>L1</u> NAVE IN AUTOMOTIVE MICONDUCTORS	
			TRACK G		
	12:55 PM - 2:25 PM	STATE OF	PANEL DISCUSSION STATE OF AUTONOMOUS VEHICLE DEVELOPMENT: MOVING FORWARD WITH SAFE CARS TRACK G	i MOVING FORWARD WITH SAFE (ARS
	2:25 PM - 2:30 PM		BREAK		
				SESSION 2C.1	
		SESSION 2A	SESSION 2B	EFFICIENT AI COMPUTING	SESSION 2D
	2:30 PM - 3:50 PM	LOW POWER COMPUTATION TECHNIQUES AND CONCEPTS TRACK A	HARDWARE-SOFTWARE CO-DESIGN OF EMBEDDED AI FOR NEXT-GENERATION IOT SYSTEMS TRACK B	SESSION 2C.2 EDA METHODOLOGIES FOR SECURE AND ERROR RESILIENT HARDWARE DESIGN	ANALOG, NANOTUBE, AND QUANTUM RELEVANCE OF MACHINE LEARNING TRACK D
				TRACK C	
			END OF DAY 1		

PROGRAM AT A GLANCE - THURSDAY

ISOFD'	SOED'21 PROGRA	RAM AT A GI ANCE			
DATE	TIME				
THURSDAY	8:50 AM - 9:00 AM		WELCOME & INTRODUCTION	NUCTION	
4/8/2021			KEYNOTE SPEECH - PLENARY SESSION P2 TRACK G	RY SESSION P2	
	9:00 AM -9:35 AM	RAVIS	CARS DRIVING CHIPS OR CHIPS DRIVING CARS? RAVI SUBRAMANIAN, PH.D., SENIOR VICE PRESIDENT - IC VERIFICATION, SIEMENS EDA TRACK 6	PS DRIVING CARS? IENT - IC VERIFICATION, SIEMENS ED/	T
	0.35 AM-10.20 AM	<u>SESSION PW1</u> POSTER AND WIP PAPERS	<u>SESSION PW2</u> POSTER AND WIP PAPERS	<u>Session PW3</u> POSTER AND WIP PAPERS	<u>SESSION PW4</u> POSTER AND WIP PAPERS
		TRACK A	TRACK B	TRACK C	TRACK D
	10:20 AM - 10:25 AM		BREAK		
	10:25 AM - 12:05 PM	S ROBUST AND EI	SESSION 3B EDA METHODOLOGIES FOR DESIGN PLANNING AND CHARACTERIZATION	<mark>SESSION 3C</mark> REVERSE ENGINEERING AND HARDWARE OBFUSCATION	<mark>5ESSION 3D</mark> APPLICATION OF AI/ML IN HARDWARE SECURITY
		TRACK A	TRACK B	TRACK C	TRACK D
	112:05 PM -12:35 PM		BREAK		
			EMBEDDED TUTORIAL 2	IAL 2	
	12:35 PM-1:35 PM	FABIO	LARGE-SCALE QUANTUM COMPUTERS: THE NEED FOR CRYO-CMOS FABIO SEBASTIANO - DELFT UNIVERSITY OF TECHNOLOGY, DELFT, THE NETHERLANDS	: THE NEED FOR CRYO-CMOS HNOLOGY, DELFT, THE NETHERLAND [:]	S
			TRACK G		
	1:35 PM -1:40 PM		BREAK		
	M9 05:2- M9 04:1	SESSION 4A DESIGN TECHNIQUES & METHODOLOGIES FOR AN ENERGY-EFFICIENT SYSTEM	<u>SESSION 4B</u> CAD FOR SYSTEM ANALYSIS AND OPT IMIZATION	SESSION 4C MEMORY AND ARCHITECTURE LEVEL SECURITY	Session 4D.1 Solunid Soc/CHIPLETS COMMUNICATION AND COMPUTATION CHALLENGES SESSION 4D.2 N-MEMORY AND QUANTUM COMPUTING TECHNOLOGIES
		TRACK A	TRACK B	TRACK C	SESSION 4D.3 RELIABILITY IN NEURAL NETWORKS
					I KACK U
			END OF DAY 2		

			EMBEDDED TUTORIAL 3	PUTTING AI ON DIET: TINYML AND EFFICIENT DEEP LEARNING PROF. SONG HAN, MIT EECS	TRACK G	EMEEDED TUTORIAL4 SECURITY CHALLENGES AND OPPORTUNITIES AT THE INTERSECTION OF ARCHITECTURE AND ML/AI PROF. NAEL ABU-GHAZALEH , UNIVERSITY OF CALIFORNIA, RIVERSIDE	IKACK G	BREAK				END OF DAY 3
	ISQEU'ZI PROGRAM AI A GLANCE					SECURITY CHAL			SESSION 5A	IOT AND WEARABLE COMPUTING	TRACK A	
	ADONY 12	TIME		9:00 AM - 10:00 AM		10:00 AM - 11:00 AM		11:00 AM - 11:10 AM		11:10 AM -12:30 PM		
12	ISQEU	DATE	FRIDAY	4/9/2021								

PROGRAM AT A GLANCE - FRIDAY

Wednesday April 7 9:20 AM - 9:55 AM Track G

Confluence of AI/ML with EDA and Software Engineering



Arun Venkatachar Vice President, Artificial Intelligence and Central Engineering , Synopsys

Investments into AI/ML to solve EDA problems with ever-increasing complexities of chip-design is starting to come to light. Recent product announcements like the DSO.ai from Synopsys revolutionizes chip design by massively scaling exploration of options in design workflows. Similarly, there are many applications in production solving different challenges in areas like verification, place & route, dfm etc., that have harnessed the power of AI/ML, Big-Data and Compute to provide a new set of tools and techniques for EDA to address both existing and new challenges. Not only do these technologies aid EDA, they are also helping us address challenges during software engineering development of these complex EDA products. By harnessing the data from code, tests, and bugs one can now improve product quality, improve productivity, and provide greater customer experience. In my talk I will be also going over such applications that are in production. With such potential, companies now need to build good data strategies to harness these benefits across their organizations. They will also need to invest in good data and AI/ML infrastructures to expedite building these solutions. It is now time to have data generate algorithms instead of the other way around! While these investments are starting to come to fruition, semiconductor design industry is still in the early stages and future promise is very alluring and exciting.

About Arun Venkatachar

Arun Venkatachar is Vice President of Artificial Intelligence & Central Engineering at Synopsys. He is responsible for leading Synopsys' Artificial Intelligence strategy and development, along with driving Synopsys core EDA engineering infrastructure, tooling and operations. He has over 20+ years of experience in building EDA products in the areas of compilers and debuggers and is currently focused on building AI/ML, Big-Data and Cloud-based solutions to solve complex problems for both internal and external customers. He has several publications and patents in the areas of distributed computing and simulation. He holds a Master's Degree in Computer Engineering. <u>Thursday</u> April 8 9:00 AM - 9:35 AM Track G

Cars Driving Chips or Chips Driving Cars?



Ravi Subramanian, Ph.D. Senior Vice President - IC Verification, Siemens EDA

The automotive industry, once driven by mechanical design, styling and fuel economy – has transformed. The road ahead for cars is now all about software and electronics in the pursuit of autonomous driving and electrification. Future automotive platforms are being shaped by new requirements around sensing, safety, and security - spanning design, manufacturing, and in-road operation. These are driving revolutionary changes in the required imaging, radar, computing, networking, and software platform technologies. In this talk, we will explore the evolution of automobile platforms and the resulting implications on IC design, manufacture, and field operation for automotive IC suppliers in the coming decade.

About Ravi Subramanian

Ravi Subramanian is Senior Vice-President of IC Verification at Siemens EDA. He joined Siemens through the acquisition of Mentor Graphics where he held the role of Vice President and General Manager of the Analog/RF/Mixed-Signal Verification Business Unit. Ravi joined Mentor through the acquisition of Berkeley Design Automation (BDA), where he was President and CEO. Prior to BDA, Ravi was at Infineon Technologies, where he was the VP and GM of the 3G WCDMA Business Group. Ravi joined Infineon through the acquisition of Morphics Technology, a fabless semiconductor company where he was the founder and VP Engineering, and then CEO. Ravi began his career at AT&T Bell Laboratories, where he worked on radio transceivers for CDMA and GSM mobile communications and led the Radio Systems Research Department. While at AT&T, Ravi won the AT&T Leadership Award for his work on digital radio platforms. Ravi received his BSEE (with honors) from the California Institute of Technology (1987). He earned his PhD in EECS from the University of California at Berkeley (1991) where he was a recipient of the prestigious UC Regent's Fellowship. He is the lead author on 18 issued United States patents on digital, analog, and RF signal processing techniques in mobile communications. With over 20 years of experience spanning semiconductor, software, wireless, and electronic design, Ravi has directly been involved in the transformations electronics, software, and semiconductors have enabled across multiple industries. Ravi is a respected and proven business leader, technologist, and entrepreneur. He is passionate about customer success, the business of technology, building teams, and fueling innovation.

Panel Discussion

Wednesday April 7

12:55 PM –2:25 PM Track G

State of Autonomous Vehicle Development: Moving Forward with Safe Cars

Panel Committee: Shigeki Tomishima - Intel Corporation (Chair) Siddha Ganju - Nvidia (Co-Chair)

Summary:

The automotive industry is going through a disruptive phase and one of the major factors causing this disruption is autonomous cars. The digitalization of the automotive industry is changing the traditional patterns of transport and mobility, and connected vehicles, self-driving vehicles, vehicles that are increasingly connected to the internet and equipped with electromechanical controls are defining some of today and most of the future automotive industry. Though there is strong demand from users, how realistic is the future of autonomous vehicles? Is the safety of autonomous cars an issue for drivers and will potential safety issues cause the autonomous vehicle development to crash? Is the mobility trend shifting towards ride sharing? What new challenges and opportunities do driverless cars bring to the microelectronic industry? What are the safety and security constraints? What are the implications of the inclusion of Al hardware and software? Join us to listen to our panelist's thoughts on the subject.

> Panelists: Nirmal R. Saxena - NVIDIA Lee Harrison - Siemens EDA James Herman - CMU/Roborace Sweta Mehta - Tata Consultancy Services Srijani Dey - DXC Technology

> > Modedrator: Aditya Sharma - Microsoft

Embedded Tutorial 1

Wednesday April 7

11:50 AM -12:50 PM Track G

Semiconductors for the next wave in Automotive



Clara Otero Pereza NXP Semiconductors

Summary:

This tutorial will provide insights on the NXP vision on mobility of the future: NXP is advancing intelligent transport systems and electrification in order to shape a future in which zero emissions, zero road fatalities and maximum convenience will become reality. ADAS – Advanced Driver Assistance Systems – will come within everyone's reach and provide the safe and increasingly autonomous experiences that will reshape our relationship to transport. The technologies of the Automated Driving Domain will soon allow passengers to experience the ultimate in personalized and connected convenience as vehicles seamlessly Sense, Think, and Act on real-time road situations.

About Clara Otero Pereza

Clara Otero Pérez is Director Systems Innovations for Automotive at NXP Semiconductor in Eindhoven (NL). She is responsible for scouting new systems and applications where NXP's products would play a role and build proof of concepts and demonstrators for those new applications such as cooperative connected car, autonomous driving and UAV. After graduating in Physics by the University of Santiago de Compostela in Spain, she started to work for Philips Research in Eindhoven (NL) as a research scientist in the field of real-time systems and multimedia processors. In 2006 she moved to NXP and started working on automotive and secure connectivity related projects. In 2008 she became department manager driving innovation activities both internal as well as with partners in subsidy projects in the areas of IoT, connected car and cooperative mobility. <u>Thursday April 8</u> 12:35 PM -13:35 PM Track G

Large-Scale Quantum Computers: The need for Cryo-CMOS



Dr. Fabio Sebastiano Delft University of Technology, Delft, The Netherlands

Summary:

Quantum computers hold the promise to change our everyday lives in this century in the same radical way as the classical computer did in the last century, by efficiently solving problems that are intractable today, such as large number factorization and simulation of quantum systems. Quantum computers operate by processing information stored in quantum bits (qubits), which must typically operate at cryogenic temperature. Today the qubits are mostly controlled by conventional electronics working at room temperature. This thermal gap can be readily bridged by a few wires since today's quantum computers employ only a few qubits.

However, practical quantum computers will require more than thousands of qubits, making this approach impractical. A solution is to build the qubit electrical interface using CMOS integrated circuits operate at cryogenic temperature (cryo-CMOS), hence very close to the qubits. This talk will give a brief introduction to quantum computers and their operations, followed by a description of their hardware implementation and their requirements in terms of electronic control and read-out, including the need for modeling the quantum/classical interface. Next, we will review the behavior of commercial CMOS devices and the available cryogenic device models required for circuit design. The demonstration of several state-of-the-art cryo-CMOS circuits and systems, both for qubit drive and readout, and their verification with qubits will be described, highlighting challenges and opportunities. Finally, we will outline the prospects towards qubit/electronics integration to enable the large-scale quantum computers required to address future world-changing computational problems.

About Fabio Sebastiano

Fabio Sebastiano holds degrees in Electrical Engineering from University of Pisa, Italy (BSc, 2003; MSc, 2005) from Sant'Anna school of Advanced Studies, Pisa, Italy (MSc, 2006) and from Delft University of Technology, The Netherlands (PhD, 2011). From 2006 to 2013, he was with NXP Semiconductors Research in Eindhoven, The Netherlands. In 2013, he joined Delft University of Technology, where he is currently an Associate Professor and the Research Lead for the Quantum Computing Division of QuTech. He has authored or co-authored one book, 11 patents, and over 70 technical publications. His main research interests are sensor read-outs, frequency references, cryogenic electronics, and quantum computing. Dr. Sebastiano was the co-recipient of the best student paper award at ISCAS in 2008, the best paper award at IWASI in 2017, and the best IP award at DATE in 2018. He is a senior member of IEEE, a TPC member for RFIC and IMS, and has served as Distinguished Lecturer of the IEEE Solid-State Circuit Society.

Friday April 9 9:00 AM - 10:00 AM Track G

Putting AI on Diet: TinyML and Efficient Deep Learning



Prof. Song Han MIT EECS

Summary:

Machine learning on tiny IoT devices based on microcontroller units (MCU) is appealing but challenging: the memory of microcontrollers is 2-3 orders of magnitude less even than mobile phones. We propose MCUNet, a framework that jointly designs the efficient neural architecture (TinyNAS) and the lightweight inference engine (TinyEngine), enabling ImageNet-scale inference on microcontrollers. TinyNAS adopts a two-stage neural architecture search approach that first optimizes the search space to fit the resource constraints, then specializes the network architecture in the optimized search space. TinyNAS can automatically handle diverse constraints (i.e. device, latency, energy, memory) under low search costs. TinyNAS is co-designed with TinyEngine, a memory-efficient inference library to expand the design space and fit a larger model. TinyEngine adapts the memory scheduling according to the overall network topology rather than layer-wise optimization, reducing the memory usage by 2.7x, and accelerating the inference by 1.7-3.3x compared to TF-Lite Micro and CMSIS-NN. MCUNet is the first to achieves >70% ImageNet top1 accuracy on an off-the-shelf commercial microcontroller, using 3.6x less SRAM and 6.6x less Flash compared to quantized MobileNetV2 and ResNet-18. On visual&audio wake words tasks, MCUNet achieves state-of-the-art accuracy and runs 2.4-3.4x faster than MobileNetV2 and ProxylessNAS-based so-lutions with 2.2-2.6x smaller peak SRAM. Our study suggests that the era of always-on tiny machine learning on IoT devices has arrived.

About Song Han

Song Han is an assistant professor in MIT EECS. His research focuses on efficient deep learning computing. He has proposed "deep compression" and "efficient inference engine" that first exploited model compression and weight sparsity in deep learning accelerators, which has been integrated into many commercial AI chips/frameworks. Recently he is interested in efficient and small NN design with AutoML and NAS. He is a recipient of NSF CAREER Award and MIT Technology Review Innovators Under 35. He earned a PhD in electrical engineering from Stanford University. synthesis algorithms.

Friday April 9

10:00 AM-11:00 AM Track G

Security challenges and opportunities at the Intersection of Architecture and ML/AI



Prof. Nael Abu-Ghazaleh University of California, Riverside

Summary:

Machine learning is an increasingly important computational workload as data-driven deep learning models are becoming increasingly important in a wide range of application spaces. Computer systems, from the architecture up, have been impacted by ML in two primary directions: (1) ML is an increasingly important computing workload, with new accelerators and systems targeted to support both training and inference at scale; and (2) ML supporting architecture decisions, with new machine learning based algorithms controlling systems to optimize their performance, reliability and robustness. In this talk, I will explore the intersection of security, ML and architecture, identifying both security challenges and opportunities. Machine learning systems are vulnerable to new attacks including adversarial attacks crafted to fool a classifier to the attacker's advantage, membership inference attacks attempting to compromise the privacy of the training data, and model extraction attacks seeking to recover the hyper parameters of a (secret) model. Architecture can be a target of these attacks when supporting ML, but also provides an opportunity to develop defenses against them, which I will illustrate with three examples from our recent work. First, I show how ML based hardware malware detectors can be attacked with adversarial perturbations to the Malware and how we can develop detectors that resist these attacks. Second, I will also show an example of a microarchitectural side channel attacks that can be used to extract the secret parameters of a neural network and potential defenses against it. Finally, I will also discuss how architecture can be used to make ML more robust against adversarial and membership inference attacks using the idea of approximate computing. I will conclude with describing some other potential open problems.

About Nael Abu-Ghazaleh

Nael Abu-Ghazaleh is a Professor with joint appointment in the CSE and ECE departments at the University of California, Riverside, and the director of the Computer Engineering program. His research interests include architecture support for security, high performance computing architectures, and networking and distributed systems. His group's research has lead to the discovery of a number of vulnerabilities in modern architectures and operating systems which have been reported to companies and impacted commercial products. He has published over 200 papers, several of which have been nominated or recognized with best paper awards. He is an ACM distinguished member, and IEEE distinguished visitor.

SESSION 1A

Wednesday April 7

Advanced Analog Design and Concepts

Chair: Nihaar Mahatme, NXP Co-Chair: Srinivasan Gopal, Intel Corporation

10:00AM

1A.1

PVT and Aging Degradation Invariant Automated Optimization Approach for CMOS

127 Low-Power High-Performance VLSI Circuits

Hema Sai Kalluru¹, Prasenjit Saha², Andleeb Zahra², Zia Abbas³ ¹IIIT Hyderabad, ²International Institute of Information Technology Hyderabad, ³International Institute of Information Technology (IIIT), Hyderabad

10:20AM

1A.2

Design Space Extrapolation for Power Delivery Networks using a Transposed Convolutional Net

Osama Waqar Bhatti and Madhavan Swaminathan Georgia Institute of Technology

10:40AM

1A.3

A Low Power Fully-Digital Multi-Level Voltage Monitor Operating in a Wide Voltage

137 Range for Energy Harvesting IoT

Shima Sedighiani¹, Kamlesh Singh², Roel Jordans¹, Pieter Harpe¹, Jose Pineda de Gyvez¹

¹Eindhoven university of technology, ²Eindhoven University of Technology (TU/e)

11:00AM

1A.4

163 A Resistorless NanoWatt CMOS Voltage Reference with High PSRR Naveed Naveed and Jeff Dix

University Of Arkansas

SESSION 1B

Wednesday April 7

Verification and Fault Analysis of Circuits

Chair: Fei Su, Intel Corporation Co-Chair: Sreejit Chakravarty, Intel Corporation

10:00AM

1B.1

Gate-Level Graph Representation Learning: A Step Towards the Improved Stuck-at

145 Faults Analysis

Aneesh Balakrishnan¹, Dan Alexandrescu¹, Maksim Jenihhin², Thomas Lange¹, Maximilien Glorieux¹ ¹IROC Technologies, ²Tallinn University of Technology

10:20AM

1B.2

174 Efficient Reachability Analysis Based on Inductive Invariant Using X-value Based Flipflop Selection

Ryogo Koike and Masahiro Fujita University of Tokyo

10:40AM

1B.3

220 Word-Level Multi-Fix Rectifiability of Finite Field Arithmetic Circuits

Vikas Rao¹, Irina Ilioaea², Haden Ondricek¹, Priyank Kalla¹, Florian Enescu³ ¹University of Utah, ²Louisiana State University Shreveport, ³Georgia State University

11:00AM

1B.4

Cell-Aware Diagnosis of Customer Returns Using Bayesian Inference

161 Safa Mhamdi¹, Patrick Girard², Arnaud Virazel³, Alberto Bosio⁴, Aymen Ladhar⁵
 ¹LIRMM - University of Montpellier, ²LIRMM / CNRS, ³LIRMM, ⁴Lyon Institute of Nanotechnology, ⁵STMicroelectronics

SESSION 1C

Wednesday April 7

Emerging Devices and Technologies

Chair: Arijit Banerjee, AMD Co-Chair: Rasit Topaloglu, IBM

10:00AM

1C.1

Achieving Wave Pipelining in Spin Wave Technology

Abdulqader Mahmoud¹, Frederic Vanderveken², Christoph Adelmann², Florin Ciubotaru², Said Hamdioui³, Sorin Cotofana³
 ¹TU Delft, ²IMEC, ³Delft University of Technology

10:20AM

1C.2

Architecture, Dataflow and Physical Design Implications of 3D-ICs for DNN-

205 Accelerators

Jan Moritz Joseph¹, Ananda Samajdar², Lingjun Zhu², Rainer Leupers¹, Sung Kyu Lim³, Thilo Pionteck⁴, Tushar Krishna²

¹RWTH Aachen University, ²Georgia Institute of Technology, ³Georgia Tech, ⁴Ottovon-Guericke-University Magdeburg

10:40AM

1C.3

RobustONoC: Fault-Tolerant Optical Networks-on-Chip with Path Backup and Signal Reflection

226 Yu-Kai Chuang¹, Yong Zhong², Yi-Hao Cheng², Bo-Yi Yu², Shao-Yun Fang², Bing Li³, Ulf Schlichtmann³

¹Technische Universität München, ²National Taiwan University of Science and Technology, ³Technical University of Munich

11:00AM 1C.4

230 Decomposition-Based Watermarking of Quantum Circuits Vedika Saravanan¹ and Samah Saeed² ¹City College of New York, City University of New York, ²City College of New York

SESSION 1D

Wednesday April 7

Applied Machine Learning for Hardware Cybersecurity

Chair: **Hossein Sayadi**, California State University Long Beach Co-Chair: **Mehrdad Aliasgari**, California State University Long Beach

10:00AM

1D.1

Machine Learning-Assisted Website Fingerprinting Attacks with Side-Channel Information: A Comprehensive Analysis and Characterization

271 han wang¹, Hossein Sayadi², Avesta Sasan³, Sai Manoj Pudukotai Dinakarrao³, Setareh Rafatirad¹, Houman Homayoun³
 ¹university of California, Davis, ²California State University, Long Beach, ³George Mason University

10:20AM

1D.2

When Machine Learning Meets Hardware Cybersecurity: Delving into Accurate Zero-Day Malware Detection

272 Zhangying He¹, Tahereh Miari², Hosein Mohammadi Makrani³, Mehrdad Aliasgari¹, Houman Homayoun⁴, Hossein Sayadi¹
 ¹California State University, Long Beach, ²California State Polytechnic University,

Pomona, ³University of California, Davis, ⁴University of California Davis

10:40AM **1D.3**

273 Leveraging Deep CNN and Transfer Learning for Side-Channel Attack Amit Garg and Nima Karimian San Jose State University

11:00AM

1D.4

274 Monotonic-HMDs: Exploiting Monotonic Features to Defend Against Evasive Malware

Md Shohidul Islam, Behnam Omidi, Khaled N. Khasawneh George Mason University

SESSION 2A

Wednesday April 7

Low Power Computation Techniques and Concepts

Chair: Marshnil Dave, Lion Semiconductor Co-Chair: Na Gong, University of South Alabama

2:30PM

2A.1

Flash ADC Utilizing Offset Voltage Variation With Order Statistics Based

Comparator Selection

Takehiro Kitamura, Mahfuzul Islam, Takashi Hisakado, Osami Wada Kyoto University

2:50PM

2A.2

109 Self-Learning Analog Comparator with Adaptive Sampling Rate Scheme for Energy Optimization in Continuous Input Monitoring Applications. *G ANAND KUMAR and VEERAMANIKANDAN RAJU*

TEXAS INSTRUMENTS INDIA PVT LTD

3:10PM **2A.3**

136 ACLA: An Approximate Carry-Lookahead Adder with Intelligent Carry Judgement and Correction

Shobhit Belwal, Rajat Bhattacharjya, Kaustav Goswami, Dip Sankar Banerjee Indian Institute of Information Technology Guwahati

SESSION 2B

Wednesday April 7

Hardware-Software Co-Design of Embedded AI for Next-Generation IoT Systems

Chair: **Mimi Xie**, University of Texas at San Antonio Co-Chair: **Abhilash Goyal**, Velodyne

2:30PM

2B.1

An End-to-end Multi-task Object Detection using Embedded GPU in Autonomous Driving

Shanglin Zhou¹, Mimi Xie², Yufang Jin², Fei Miao¹, Caiwen Ding¹ ¹University of Connecticut, ²The University of Texas at San Antonio

2:50PM

2B.2

SAC: A Novel Multi-hop Routing Policy in Hybrid Distributed IoT System based on

250 Multi-agent Reinforcement Learning

Wen Zhang¹, Tao Liu², Mimi Xie³, Jun Zhang⁴, Chen Pan¹ ¹Texas A&M University-Corpus Christi, ²Lawrence Technological University, ³The University of Texas at San Antonio, ⁴Harvard University 3:10PM

2B.3

Improving DNN Fault Tolerance using Weight Pruning and Differential Crossbar Mapping for ReRAM-based Edge AI

Geng Yuan¹, Zhiheng Liao², Xiaolong Ma¹, Yuxuan Cai¹, Zhenglun Kong¹, Xuan
 Shen¹, Jingyan Fu², Zhengang Li¹, Chengming Zhang³, Hongwu Peng⁴, Ning Liu¹, Ao Ren⁵, Jinhui Wang⁶, Yanzhi Wang¹

¹Northeastern University, ²North Dakota State University, ³Washington State University, ⁴University of Connecticut, ⁵Chongqing University, ⁶University of South Alabama

3:30PM

2B.4

Accelerating Transformer-based Deep Learning Models on FPGAs using Column Balanced Block Pruning

257 Hongwu Peng¹, Shaoyi Huang¹, Tong Geng², Ang Li², Weiwen Jiang³, Hang Liu⁴, Shusen Wang⁴, Caiwen Ding¹

¹University of Connecticut, ²Pacific Northwest National Laboratory, ³University of Notre Dame, ⁴Stevens Institute of Technology

SESSION 2C.1

Wednesday April 7

Efficient AI Computing

Chair: Hongyu An, Michigan Tech University Co-Chair: Amey Kulkarni, Nvidia

2:30PM

2C.1.1

Regularization-Free Structural Pruning for GPU Inference Acceleration

263 Chuliang Guo¹, Yanbing Yang², Li Zhang¹, Shaodi Wang³, He Li⁴, Keyu Long², Xunzhao Yin¹, Cheng Zhuo¹

¹Zhejiang University, ²The Second Research Institute of Civil Aviation Administration of China, Chengdu, China, ³WITIN Tech Co. Ltd., Beijing, China, ⁴University of Cambridge, Cambridge, UK

2:50PM

2C.1.2

264 Low-power Analog and Mixed-signal IC Design of Multiplexing Neural Encoder in Neuromorphic Computing

Honghao Zheng¹, Nima Mohammadi¹, Kangjun Bai², Yang (Cindy) Yi² ¹Virginia Tech, Blacksburg, VA, ²Virginia Tech

3:10PM

2C.1.3

275 Machine Learning for Evaluating the Impact of Manufacturing Process Variations in High-Speed Interconnects

*Cemil Geyik*¹, *Zhichao Zhang*¹, *Kemal Aygun*¹, *James Aberle*² ¹Intel Corporation, ²Arizona State University

SESSION 2C.2

Wednesday April 7

EDA Methodologies for Secure and Error Resilient Hardware Design

Chair: **Srinivas Katkoori**, University of South Florida Co-Chair: **Sheikh Ariful Islam**, University of Texas Rio Grande Valley

 3:30PM
 2C.2.1
 Secure High-Level Synthesis: Challenges and Solutions Nitin Pundir¹, Farimah Farahmandi², Mark Tehranipoor²
 ¹Ansys, Inc (Intern), ²University of Florida
 3:50PM
 2C.2.2
 An Error Resilient Design Platform for Aggressively Reducing Power, Area and Routing Congestion Tung-Liang Lin and Sao-Jie Chen Graduate Institute of Electronics Engineering, National Taiwan University

SESSION 2D

Wednesday April 7

Hardware Security in Systems and Quantum Computing

Chair: **Anupam Chattopadhyay**, Nanyang Technological University Co-Chair: **TBD**, TBD

2:30PM

2D.1

Deep Learning assisted Cross-Family Profiled Side-Channel Attacks using Transfer

245 Learning

Dhruv Thapar¹, Manaar Alam¹, Debdeep Mukhopadhyay² ¹Indian Institute of Technology Kharagpur, ²Department of Computer Science and Engineering, Indian Institute of Technology Kharagpur

2:50PM

2D.2

246 Impact of Noise on the Resilience and the Security of Quantum Computing Abdullah Ash- Saki, Mahabubul Alam, Swaroop Ghosh Pennsylvania State University

3:10PM

2D.3

247 Sandbox Detection Using Hardware Side Channels Yehonatan Lusky and Avi Mendelson

Technion

3:30PM

2D.4

248 Trusted Electronic Systems with Untrusted COTS

Shuo Yang, Prabuddha Chakraborty, PATANJALI SLPSK, SWARUP BHUNIA University of Florida

SESSION PW1

Thursday April 8

Poster and WIP Session 1

Chair: Ali Iranmanesh, Silicon Valley Polytechnic Institute

132	9:35AM PW1.1 Toward Intelligence in Communication Networks: A Deep Learning Identification Strategy for Radio Frequency Fingerprints Kangjun Bai ¹ , Clare Thiem ² , Nathan McDonald ² , Lisa Loomis ² , Yang Yi ¹ ¹ Virginia Tech, ² Air Force Research Laboratory
201	9:40AM PW1.2 Three-dimensional Memristive Deep Neural Network with Programmable Attention Mechanism Hongyu An ¹ , Kangjun Bai ² , Yang Yi ² ¹ Michigan Technological University, ² Virginia Tech
170	9:45AM PW1.3 Detection Limit for Intermediate Faults in Memristor Circuits Rasika Joshi and John Acken Portland State University
177	9:50AM PW1.4 Enabling ECC and Repair Features in an eFuse Box for Memory Repair Applications Miguel F Costa ¹ and Srikanth Beerla ²

¹Intel Corporation, ²Intel Technology Pvt Ltd

9:55AM

PW1.5

A crosstalk modelling method between a power supply and a nearby signal in highdensity interconnection PCBs

Faten Sahel¹, Pascal Guilbault¹, Farouk Vallette², Sylvain Feruglio² ¹ATOS, ²LIP6

10:00AM

PW1.6

168 Formal Verification Aware Redundant Sequential Logic Optimization to Improve Design Utilization

Rushabh Shah and Krishna Agrawal Digital Design Engineer, Intel Technology India Pvt. Ltd

10:05AM **PW1.7**

173 A Wafer-scale Manufacturing Pathway for Fine-grained Vertical 3D-IC Technology Sachin Bhat, Sounak (Shaun) Ghosh, Sourabh Kulkarni, Mingyu Li, Csaba Andras Moritz UMass Amherst

SESSION PW2

Thursday April 8

Poster and WIP Session 2

Chair: Amey Kulkarni, Nvidia

9:35AM

PW2.1

240 Novel Memristor-based Nonvolatile D Latch and Flip-flop Designs

Zhenxing Chang¹, Aijiao Cui¹, Gang Qu², Ziming Wang¹ ¹Harbin Institute of Technology Shenzhen Graduate School, ²Univ. of Maryland, College Park 9:40AM

PW2.2

Variation Aware Timing Model of CMOS Inverter for an Efficient ECSM Characterization

 242 Lomash Chandra Acharya¹, Arvind Kumar Sharma², Venkatraman Ramakrishnan³, ajoy mandal³, Sudeb Dasgupta⁴, Anand Bulusu⁵
 ¹Indian Institute of technology,roorkee, ²University of Minnesota, ³Texas Instruments, ⁴Associate Professor, IIT Roorkee, ⁵Indian Institute of Technology Roorkee

9:45AM

PW2.3

232 Reconfiguring the Mux-Based Arbiter PUF using FeFETs

*Srinivasa Varadan Ramanujam*¹ *and Wayne Burleson*² ¹University of MAssachusetts- Amherst, ²UMass- Amherst

9:50AM

PW2.4

A Lightweight Delay-based Authentication Scheme for DMA Attack Mitigation

156 Yutian Gui, Ali Shuja Siddiqui, Geraldine Shirley Nicholas, Marcus Hughes, Fareena Saqib

University of North Carolina at Charlotte

9:55AM

PW2.5

106 3D IC Packaging Utilizing a Metal structure for Heat Reduction, Noise Shielding, and High Interconnect Density

Nahid Mirzaie and Ronald Rohrer Southern Methodist University

10:00AM

PW2.6

147 **Chip Package Co-design and Physical Verification for Heterogeneous Integration.** *Rajsaktish Sankaranarayanan, Archanna Srinivasan, Arch Zaliznyak, Sreelekha Mittai* Intel Corporation

10:05AM

¹⁹⁷ PW2.7

Analysis and Design of a 5G Multi-Mode Power Amplifier using 130 nm CMOS

technology

*Marwa Mansour*¹, *Abdelhalim Zekry*², *Mohammed K. Ali*³, *Heba Shawkey*¹ ¹Electronics Research Institute, ²Ain shams University, ³Fauyoum University

10:10AM

PW2.8

A Comprehensive Multi-Voltage Design Platform for System-Level Validation of Standard Cell Library Akshay Kamath, Bharath Kumar, Sunil Aggarwal, Subramanian Parameswaran, Mitesh Goyal, Parag Lonkar, Somasunder Sreenath

Samsung Semiconductor India R&D

SESSION PW3

Thursday April 8

Poster and WIP Session 3

Chair: Sara Tehranipoor, Santa Clara University

9:35AM

PW3.1

149 ChipAdvisor: A Machine Learning Approach for Mapping Applications to Heterogeneous Systems

Hiwot Tadese Kassa, Tarunesh Verma, Todd Austin, Valeria Bertacco University of Michigan

9:40AM

PW3.2

165 Integration of Minimum Energy Point Tracking and Soft Real-Time Scheduling for Edge Computing

Takumi Komori¹, Yutaka Masuda¹, Jun Shiomi², Tohru Ishihara¹ ¹Nagoya University, ²Kyoto University 9:45AM

PW3.3

140 Global multi-voltage interface unit for diverse digital logic

Manisha Girish¹, Karthik Suman², Sandeep Motebennur¹, Krishna Prasanna¹, Prashanth N¹ ¹Intel Corporation, ²Intel Corp

9:50AM **PW3.4**

141 Achieving Zero ADC Production Test Time with Self-calibration and BIST Maher Sarraj, Haydar Bilhan, Wahed Mohammed Texas Instruments, Inc.

9:55AM

PW3.5

143 LEC Vulnerability On Constant Propagation Sandeep Kumar Srivastav¹, Ming Yi Lim², Babu Trp², Jeevan K Y² ¹Intel India, ²Intel

10:00AM

PW3.6

166 FPGA Accelerated Parameterized Cache Simulator

Shivani Shah¹, Sahithi Meenakshi Vutakuru¹, Nanditha Rao² ¹International Institute of Information Technology Bangalore, ²IIIT Bangalore

10:05AM

PW3.7

175 Back-Bias Modulated UTBB SOI for System-on-Chip I/O Cells

Ming Yu Chang¹, Po Yu Chao², Meng Hsueh Chiang² ¹+886 919181317, ²National Cheng Kung University

SESSION PW4

Thursday April 8

Poster and WIP Session 4

Chair: Abhilash Goyal, Velodyne

9:35AM

PW4.1

190 SALAH: Simulation-Assisted LAyout Hierarchy Construction Sherif Hany, Emad Hegazi, Hani Ragai

Ain Shams university

9:40AM

PW4.2

A New Foe in GPUs: Power Side-Channel Attacks on Neural Network

 Hyeran Jeon¹, Nima Karimian², Tamara Lehman³
 ¹University of California Merced, ²San Jose State University, ³University of Colorado Boulder

9:45AM

PW4.3

138Performance investigation of a Si/Ge Heterojunction Asymmetric Double GateDLTFET considering Temperature and ITC variations

Suruchi Sharma¹, Rikmantra Basu², Baljit Kaur² ¹NIT, ²NIT Delhi

9:50AM

PW4.4

Large-Scale Quantum System Design on Nb-based Superconducting Silicon

Interconnect Fabric

Yu-Tao Yang and Subramanian Iyer UCLA

9:55AM

199 **PW4.5**

On Synthesizing Memristor-Based Logic Circuits in Area-Constrained Crossbar Arrays

Hsin-Tsung Lee¹, Chia-Chun Lin¹, Yung-Chih Chen², Chun-Yao Wang³ ¹National Tsing Hua University, ²Yuan Ze University, ³Dept. CS, National Tsing Hua University

10:00AM

PW4.6

211 Compressing CNNs by Exponent Sharing in Weights using IEEE Single Precision Format

Prachi Kashikar and Sharad Sinha Indian Institute of Technology Goa

10:05AM PW4.7 Infineon Platform for SoC IO Ring and Package Design Sathvik Tarikere Sathvanarayana¹ Anna-Antonia Berger² Make

244 Sathvik Tarikere Sathyanarayana¹, Anna-Antonia Berger², Mahesh Simpy Kumar³, Akbay Erkan², Ramkrishna Paira³
 ¹Infineon Technologies Pvt Ltd, ²Infineon Technologies AG Neubiberg, Germany, ³Infineon Technologies India Pvt. Ltd, Bangalore, India

SESSION 3A

Thursday April 8

Robust and Efficient AI Computing

Chair: Cindy Yi, Virginia Tech Co-Chair: Amey Kulkarni, Nvidia

10:25AM

3A.1

Diverse Knowledge Distillation (DKD): A Solution for Improving The Robustness of Ensemble Models Against Adversarial Attacks

Ali Mirzaeian¹, Jana Kosecka¹, Homan Homayoun², Tinoosh Mohsenin³, Avesta Sasan¹ ¹George Mason University, ²University of California, Davis, ³University of Maryland, Baltimore County 10:45AM

3A.2

Conditional Classification: A Solution for Computational Energy Reduction

Ali Mirzaeian¹, Sai Manoj Pudukotai Dinakarrao¹, Ashkan Vakil¹, Homan Homayoun², Avesta Sasan¹

¹George Mason University, ²University of California, Davis

11:05AM

3A.3

A Lightweight Error-Resiliency Mechanism for Deep Neural Networks

 Brunno F. Goldstein¹, Victor C. Ferreira¹, Sudarshan Srinivasan², Dipankar Das², Alexandre S. Nery³, Sandip Kundu⁴, Felipe M. G. França¹
 ¹Federal University of Rio de Janeiro, ²Intel Labs, ³University of Brasilia, ⁴University of Massachusetts Amherst

11:25AM

3A.4

158 A Three-dimensional (3D) Memristive Spiking Neural Network (M-SNN) System Hongyu An¹, Mohammad Shah Al-Mamun², Marius Orlowski², Yang Yi² ¹Michigan Technological University, ²Virginia Tech

11:45AM

3A.5

207 **Exploring Fault-Energy Trade-offs in Approximate DNN Hardware Accelerators** *Ayesha Siddique¹, Kanad Basu², Khaza Anuarul Hoque¹* ¹University of Missouri, ²University of Texas at Dallas

SESSION 3B

Thursday April 8

EDA Methodologies for Design Planning and Characterization

Chair: **Srinivas Katkoori**, University of South Florida Co-Chair: **R. Chidambaranathan**, Synopsys, Inc.

10:25AM

3B.1

150 Fast and Accurate Library Generation Leveraging Deep Learning for OCV Modelling *Eunice Naswali*¹, *Namhoon Kim*¹, *Pravin Chandran*² ¹Intel Corporation, ²Intel Technologies India Pvt Ltd

10:45AM

3B.2

216 On the Correlation Between Resource Minimization and Interconnect-related Complexities in High-Level Synthesis

Shantanu Dutt¹, Xiuyan Zhang¹, Ouwen Shi² ¹University of Illinois at Chicago, ²Cadence Design Systems

11:05AM

3B.3

Six-track Standard Cell Libraries with Fin Depopulation, Contact over Active Gate,

180 and Narrower Diffusion Break in 7nm Technology

Tzu-Hsuan Wang, Chih-Chun Hsu, Li Kao, Bing-Yu Li, Tung-Chun Wu, Tsao-Hsuan Peng, Rung-Bin Lin Yuan Ze University

11:25AM

3B.4

125 Fast Thermal Goodness Evaluation of a 3D-IC Floorplan

Satya K. Vendra and Malgorzata Chrzanowska-Jeske Portland State University 11:45AM **3B.5**

235 Mining Message Flows from System-on-Chip Execution Traces Md Rubel Ahmed¹, Hao Zheng¹, Parijat Mukherjee², Mahesh C. Ketkar², Jin Yang² ¹University of South Florida, ²Intel

SESSION 3C

Thursday April 8

Reverse Engineering and Hardware Obfuscation

Chair: **Ioannis Savidis**, Drexel University Co-Chair: **Nima Karimian**, SJSU

10:25AM

3C.1

172 **SOMA: Security Evaluation of Obfuscation Methods via Attack Sequencing** *Abdulrahman Alaql¹, Xinmu Wang², Md Moshiur Rahman¹, SWARUP BHUNIA¹* ¹University of Florida, ²Northwestern Polytechnical University

10:45AM

3C.2

183 ChaoLock: Yet Another SAT-hard Logic Locking using Chaos Computing Hadi Mardani Kamali¹, Kimia Zamiri Azar¹, Houman Homayoun², Avesta Sasan¹ ¹George Mason University, ²University of California Davis

11:05AM

3C.3

154 Profiled Power Analysis Attacks by Efficient Architectural Extension of CNN Implementation

Soroor Ghandali¹, Samaneh Ghandali², Sara Tehranipoor¹ ¹Santa Clara University, ²Google 11:25AM

3C.4

Exploring the RISC-V Vector Extension for the Classic McEliece Post-Quantum Cryptosystem

 Sabine Pircher¹, Johannes Geier², Alexander Zeh³, Daniel Mueller-Gritschneder²
 ¹HENSOLDT Cyber GmbH, Research and Development; Technical University of Munich, Department of Electrical and Computer Engineering, Professorship of Coding for Communications and Data Storage, ²Technical University of Munich, Department of Electrical and Computer Engineering, Chair of Electronic Design Automation, ³HESOLDT Cyber GmbH, Research and Development

11:45AM

3C.5

236 Defending Misspeculation-based Cache Probe Attacks Using Variable Record Table Love Sah¹, Sheikh Ariful Islam², Srinivas Katkoori¹
¹University of South Florida, ²University of Texas Rio Grande Valley

SESSION 3D

Thursday April 8

Application of AI/ML in Hardware Security

Chair: **Rajat Subhra Chakraborty**, Indian Institute of Technology Kharagpur Co-Chair: **Pranesh Santikellur**, Indian Institute of Technology Kharagpur

10:25AM **3D.1**

252 Application of Machine Learning in Hardware Trojan Detection Shamik Kundu¹, Xingyu Meng¹, Kanad Basu² ¹The University of Texas at Dallas, ²University of Texas at Dallas 10:45AM

3D.2

253 TRGP: A Low-Cost Re-Configurable TRNG-PUF Architecture for IoT

Vikash Kumar Rai¹, Somanath Tripathy², Jimson Mathew³ ¹IIT Patna, ²Indian Institute of Technology, Patna, ³University of Bristol

11:05AM

3D.3

Chaogate Parameter Optimization using Bayesian Optimization and Genetic

254 Algorithm

Rabin Yu Acharya¹, Noeloikeau F. Charlot², Md Mahbub Alam³, Fatemeh Ganji⁴, Daniel Gauthier², Domenic Forte¹ ¹University of Florida, ²Ohio State University, ³Intel, ⁴Worcester Polytechnic Institute

11:25AM

3D.4

255 Hardware Trojan Detection Method for Inspecting Integrated Circuits Based on Machine Learning

Yuze Wang¹, Peng Liu¹, Xiaoxia Han¹, Yingtao Jiang² ¹Zhejiang University, ²University of Nevada Las Vegas

11:45AM

3D.5

256 **Towards automatic and portable data loading template attacks on microcontrollers** *Unai Rioja*¹, *Lejla Batina*², *Jose Luis Flores*³, *Igor Armendariz*³

¹Radboud University, ²Radboud University Nijmegen, ³Ikerlan Technological Research Centre

SESSION 4A

Thursday April 8

Design Techniques & Methodologies for an Energy-Efficient System

Chair: Harsh Patel, AMD

Co-Chair: Georgios Keramidas, Think Silicon

1:40PM

4A.1

MACcelerator: Approximate Arithmetic Unit for Computational Acceleration

 Alice Sokolova¹, Mohsen Imani², Andrew Huang¹, Ricardo Garcia¹, Justin Morris³, Tajana Rosing⁴, Baris Aksanli⁵
 ¹University of California San Diego, ²University of California Irvine, ³University of California, San Diego, ⁴UCSD, ⁵San Diego State University

2:00PM

4A.2

Towards Row Sensitive DRAM Refresh through Retention Awareness

181 Tanmay Goel¹, Divyansh Maura², Kaustav Goswami³, Shirshendu Das⁴, Dip Sankar Banerjee³

¹Indian Institute Of Information Technology, Guwahati, ²IIIT-G, ³Indian Institute of Information Technology Guwahati, ⁴Indian Institute of Technology Ropar

2:20PM

4A.3

HardCompress: A Novel Hardware-based Low-power Compression Scheme for DNN

208 Accelerators

Ayush Arunachalam¹, Shamik Kundu¹, ARNAB RAHA², Suvadeep Banerjee³, Suriya Natarajan², Kanad Basu¹

¹University of Texas at Dallas, ²Intel Corporation, ³Intel Labs, Intel

2:40PM

4A.4

Brightening the Optical Flow through Posit Arithmetic

Vinay Saxena¹, Ankitha Reddy¹, Jonathan Neudorfer², John Gustafson³, Sangeeth S.
 Nambiar⁴, Rainer Leupers⁵, Farhad Merchant⁶

¹Corporate Research, Robert Bosch, Bangalore, ²Robert Bosch GmbH, ³National University of Singapore, ⁴Robert Bosch, ⁵RWTH Aachen University, ⁶Institute for Communication Technologies and Embedded Systems, RWTH Aachen University

3:00PM

4A.5

DAMUS: Dynamic Allocation based on Write Frequency in MUlti-Retention STT-RAM based Last Level Caches

239 Mayank Baranwal¹, Udbhav Chugh¹, Shivang Dalal¹, Sukarn Agarwal², Hemangee Kapoor¹

¹Indian Institute of Technology Guwahati, ²Indian Institute of Technology (BHU) Varanasi

SESSION 4B

Thursday April 8

CAD for System Analysis and Optimization

Chair: Srini Krishnamoorthy, Intel, Bangalore Co-Chair: Murthy Palla, Synopsys Inc.

1:40PM

4B.1

185 A Novel NBTI-Aware Chip Remaining Lifetime Prediction Framework Using Machine Learning

Yu-Guang Chen¹, Ing-Chao Lin², Yong-Che Wei³ ¹National Central University, ²National Cheng Kung University, ³Yuan Ze University 2:00PM

4B.2

210 Minimally Allocating Always-on State Retention Storage for Supporting Power

Gating Circuits

Soomin Kim and Taewhan Kim Seoul National University

2:20PM

4B.3

160 Automatic Generation of Translators for Packet-Based and Emerging Protocols Brian Crafton¹, Arijit Raychowdhury¹, Sung Kyu Lim² ¹Georgia Institute of Technology, ²Georgia Tech

2:40PM

4B.4

258 SoC Trust Validation Using Assertion-Based Security Monitors

Khitam Alatoun¹, Bharath Shankaranarayanan¹, Shanmukha Murali Achyutha², Ranga Vemuri² ¹University of Cincinnati, Cincinnati, Ohio, ²University Of Cincinnati

3:00PM

4B.5

227 Analysis of Attack Surfaces and Practical Attack Examples in Open Source FPGA CAD Tools

Sandeep Sunkavilli, Zhiming Zhang, Qiaoyan Yu University of New Hampshire

SESSION 4C

Thursday April 8

Memory and Architecture Level Security

Chair: Fareena Saqib, University of North Carolina at Charlotte Co-Chair: Nima Karimian, SJSU 1:40PM

4C.1

True Random Number Generation using Latency Variations of Commercial MRAM

202 Chips

Farah Ferdaus¹, Bashir Mohammad Sabquat Bahar Talukder¹, Mehdi Sadi², Md Tauhidur Rahman¹

¹Florida International University, ²Auburn University

2:00PM

4C.2

148 CARE: Lightweight Attack Resilient Secure Boot Architecture with Onboard Recovery for RISC-V based SOC

Avani Dave¹, Nilanjan Banerjee², Chintan Patel³ ¹University of Maryland Baltimore County, ²Assistant Professor, UMBC, ³UMBC

2:20PM

4C.3

238 SeNonDiv: Securing Non-Volatile Memory using Hybrid Memory and Critical Data Diversion

Arijit Nath¹, Manik B Bhosle², Hemangee Kapoor³ ¹IIT Guwahati, India, ²IIT Guwahati, ³Indian Institute of Technology Guwahati

2:40PM

4C.4

Reliable Strong PUF Enrollment and Operation with Temperature and Voltage Optimization

Kleber Stangherlin and Manoj Sachdev University of Waterloo

3:00PM

4C.5

123 Flush-Reload Attack and its Mitigation on an FPGA Based Compressed Cache Design

Prashant Mata¹ and Nanditha Rao²

¹International Institute of Information Technology Bangalore, ²IIIT Bangalore

SESSION 4D.1

Thursday April 8

Solving SoC/Chiplets Communication and Computation Challenges

Chair: **Tobias Gemmeke**, Aachen University Co-Chair: **Rakesh Mahto**, Computer Eng. Program

1:40PM

4D.1.1

A Reconfigurable Asynchronous SERDES for Heterogenous Chiplet Interconnects

Jainaveen Sundaram Priya¹, Srinivasan Gopal¹, Erika Ramirez Lozano¹, Thomas P Thomas¹, Edward Burton¹, Tanay Karnik² ¹Intel Corporation, ²Intel

2:00PM

4D.1.2

Trends and Opportunities for SRAM Based In-Memory and Near-Memory

261 Computation

Srivatsa Srinivasa¹, Jainaveen Sundaram Priya², Dileep Kurian³, Srinivasan Gopal², Anuradha Srinivasan¹, Vijaykrishnan Narayanan⁴, Tanay Karnik¹ ¹Intel, ²Intel Corporation, ³Intel technologies, ⁴Penn State University

SESSION 4D.2

Thursday April 8

In-Memory and Quantum Computing Technologies

Chair: **Rasit Topaloglu**, IBM Co-Chair: **Vita Pi-Ho Hu**, National Taiwan University

 2:20PM
 4D.2.1
 Cross-layer Optimization Strategy for Energy-efficient and Variation-aware Inmemory Computing *Tuo-Hung Hou* National Chiao Tung University
 2:40PM
 4D.2.2
 Challenges for Building a Silicon-based Quantum Computer Jonathan Baugh

University of Waterloo

SESSION 4D.3

Thursday April 8

Reliability in Neural Networks

Chair: **Rasit Topaloglu**, IBM Co-Chair: **Vita Pi-Ho Hu**, National Taiwan University

3:00PM

4D.3.1

Runtime Long-Term Reliability Management Using Stochastic Computing in Deep

262 Neural Networks

Yibo Liu¹, Shuyuan Yu², Shaoyi Peng², Sheldon Tan³ ¹University of Califronia, Riverside, ²University of California, Riverside, ³University of California at Riverside

SESSION 5A

Friday April 9

IoT and Wearable Computing

Chair: **Prabha Sundaravadivel**, University of Texas at Tyler Co-Chair: **TBD**, TBD

11:10AM

5A.1

265 Towards Internet-of-Things for Wearable Neurotechnology

Salma Elmalaki¹, Berken Utku Demirel¹, Mojtaba Taherisadr¹, Sara Stern-Nezer¹, Jack J. Lin¹, Mohammad Al Faruque² ¹University of California, Irvine, California, ²University of California Irvine

11:30AM

5A.2

 266 Real-Time CNN Based ST Depression Episode Detection Using Single ECG-Lead LAKSHMAN TAMIL¹, Erhan Tiryaki¹, Akshay Sonawane²
 ¹University of Texas at Dallas, ²The University of Texas at Dallas

11:50AM

5A.3

267 An Interactive IoT-based framework for Resource Management in Assisted living during pandemic

Parker Wilmoth and Prabha Sundaravadivel University of Texas at Tyler

12:10PM

5A.4

268 SolicitudeSavvy: An IoT-based edge intelligent framework for monitoring anxiety in real-time

Prabha Sundaravadivel, Parker Wilmoth, Ashton Fitzgerald University of Texas at Tyler

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